

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|--|-----------------|---------------|-------------------------|---------------|
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.2 | 100.0 | 1.5 |
| | | | Subtotal | 0.2 | 100 | 1.5 |
| Lead Frame | Copper alloy | Copper (Cu) | 7440-50-8 | 60.06 | 100.0 | 454.5 |
| | | | Subtotal | 60.06 | 100 | 454.5 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 1.04 | 100.0 | 7.83 |
| | | | Subtotal | 1.04 | 100 | 7.83 |
| Mould Compound | polymer | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 0.62 | 1.6 | 4.65 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 2.5 | 6.5 | 18.91 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 5 | 13.0 | 37.82 |
| | Filler | Silica fused | 60676-86-0 | 29.98 | 78.0 | 226.9 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.27 | 0.7 | 2.04 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 0.08 | 0.2 | 0.58 |
| | | | Subtotal | 38.45 | 100 | 290.9 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.07 | 100.0 | 0.52 |
| | | | Subtotal | 0.07 | 100 | 0.52 |
| Solder Wire | Pure metal | Tin (Sn) | 7440-31-5 | 0.01 | 5.0 | 0.08 |
| | Pure metal | Silver (Ag) | 7440-22-4 | 0 | 1.5 | 0.02 |
| | Pure metal | Lead (Pb) | 7439-92-1 | 0.19 | 93.5 | 1.42 |
| | | | Subtotal | 0.2 | 100 | 1.52 |
| | | | Total | 100.02 | 100 | 756.77 |

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